



## *DIGITAL Server 7000 Series Product Change Information*

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<b>Initial Release:</b>	<b>Jan 1998</b>
<b>Current Release</b>	<b>Jun 1998</b>

This document details the following for the DIGITAL Server 7000 product change information:

- Introduction
- Product Change Summary
- BIOS Release Summary
- Product Change Release Notes
- BIOS Change Release Notes
- Customer Impact Ratings
- Future Releases

### **Introduction**

This document is meant to provide customers with a synopsis of product changes. The change information enables customers to evaluate the impact any change has on their environment. All proposed product changes are appraised for their potential impact to daily customer operations. This evaluation includes, but is not limited to such items as safety, emission requirements, functionality, compatibility, reliability, and manufacturing process. Recommendations are then made to customers on whether any action needs to be taken. On occasion, emergency changes may be implemented before they are reflected in this document.

### **Product Change Summary**

The Product Change Summary provides a overview of the "Engineering Change Orders" or ECOs that have been released. This matrix provided the part number, part description, date of release, customer impact, and brief description of the change. At this time, this document only covers Main Logic Board (MLB) and system BIOS changes. Future releases of this document will include ECO information for other major components.

## BIOS Release Summary

The BIOS Release Summary is a subset of information from the Product Change Summary. It is meant to provide an overview of just the BIOS Release history. This matrix provides the BIOS release number, date of release, customer impact, and brief description. The brief description either denotes a specific change, maintenance release, and/or new feature support. A maintenance release implies that a series of changes or problem fixes were put in place.

## Product Change Release Notes

The Product Change Release Notes provide information on each specific change. This information is meant to aid the customer in understanding in more detail what has changed and whether they need to take any action. The change descriptions include a change, solution if applicable, and a customer recommendation.

## Customer Impact Rating

For each product change a customer impact rating is given. The customer impact rating can be one of four ratings: High, Medium, Low, or None.

- HIGH** A "HIGH" rating indicates that this change has some or significant customer impact. This change may affect safety, functionality, compatibility, or reliability.
- MEDIUM** A "MEDIUM" rating indicates that this change may impact some customers or customers using certain configurations. This change will have a minor effect on reliability, functionality, or compatibility.
- LOW** A "LOW" rating indicates that this change will have a minor impact on customers. This change is typically a product improvement and/or enhancement.
- NONE** A "NONE" rating indicates that this change has no customer impact. This type of change can range from a part substitution, documentation change, or yield enhancement.

## Future Releases

Future releases of this document will incorporate information for other major system components. BIOS changes will be separated from the Main Logic Board (MLB) changes. Historically, BIOS releases were tied to MLB revision; therefore, a change in BIOS version would change the MLB revision. In the future, BIOS changes will be released independently and not affect the MLB revision.

## Systems Supported

The information outlined in this document covers the following system variants:

System Variant	Description
7100 1200R/512	Pentium Pro 200 MHZ
7100 1200 /512	Pentium Pro 200 MHZ

## Product Change Summary

Part Number	Part	Old Rev	New Rev	ECO Number	Date	Customer Impact	Change Description
FRPCSPS	Krnl	A01	A01	FRPCSPS-TA001	Nov 97	Low	Create new variation AC
54-24480-01/02	MLB	F01 A01	H01 B01	5424480-TA013	Dec 97	High	OCF back light problem for DS7100
PC932-A9	Krnl	A01	B01	PC932-TA001	Dec 97	High	New Ferrite Bead Assy. For DS7100
54-25422-01	MLB	A01	B01	5425422-TA001	Nov 97	High	Fix problem with MLB for DS7100R
54-23954-01	OCF Mod	B02	C02	5423594-TA003	Feb 98	High	Adding components to OCF for DS7100 and DS7105
PC932-A9	Krnl	A01	B01	PC932-TA002	Feb 98	High	Phase in BCIQ for DS7100-Viper
54-25422-01	MLB	B02	B03	5425422-TA003	Feb 98	Medium	Solder mask problem for DS7100R
54-25422-01	MLB	B02	B03	5425422-TA003A	Feb 98	Medium	Supplement ECO for Solder mask problem for DS7100R
54-24480-02	MLB	B02	B03	5424480-TA016	Mar 98	Medium	Modify locating holes in MLB for DS7100 and DS7105

## **ECO Number: FRPCSPS-TA001**

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Part	Krnl
Revision	A01
Component	Krnl
Severity	Low
ECO Issue Date	Nov 97
Type of Notification	Action not required
Change Description	A new variation needs to be documented.

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### **Description**

**Severity:** Low

**Description:** Add 30-49362-01 Power supply, 400WS (Qty 1) Add 99-05016-18 Assembly, D/C carton qty. is 1.

**Symptom:** N/A

### **Solution**

Document change

### **Compatibility**

N/A

### **Customer Impact/Recommendations:**

No customer impact since this change is a document change only.

## **ECO Number: 5424480-TA013**

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Part	MLB
Revision	H01 and B01
Component	MLB
Severity	High
ECO Issue Date	Dec 97
Type of Notification	Action not required
Change Description	OCP back light problem for DS7100

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### **Description**

**Severity:** High

**Description:** The OCP back light does not go out on some systems. This is caused from a problem of E23 (8242 keyboard controller chip) on the MLB.

**Symptom:** N/A

### **Solution**

Built with 21-40582-63 (8242-PE) and not 21-3902-64 (8242-PC) on MLB, and delete "120  
NOTE: 21-40582-63 can be substituted by 21-39002-64 on KPL.

### **Compatibility**

N/A

### **Customer Impact/Recommendations:**

No customer impact, it will be implemented in the manufacturing side.

## **ECO Number: PC932-TA001**

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Part	Krnl
Revision	B01
Component	Krnl
Severity	High
ECO Issue Date	Dec 97
Type of Notification	Action not required
Change Description	New Ferrite Bead Assy. For DS7100

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### **Description**

**Severity:** High

### **Description:**

1. Additional choke needed (16-25105-18) due to EMC issues.
2. The cable (17-04143-04) is not long enough to reach one of the repeaters. The bus repeater option does ship with a 1230mm cable (17-04143-03)

**Note:** This choke is on the SCSI cable (17-04143-07) which is near to the end of SBB backplane

**Symptom:** N/A

### **Solution**

1. Add new item: 16-25105-18 Ferrite Bead Assy. (qty was 0 each and is now 1 each)
2. Change the SCSI cable from 17-04143-04-03.
  - Delete 17-04143 SCSI cable 870mm (qty was 4 each and is now 0 each).
  - Delete 17-04143 SCSI cable 1230mm (qty was 0 each and is now 4 each).

### **Compatibility**

N/A

### **Customer Impact/Recommendations:**

No customer impact, it will be implemented in the manufacturing process.

## **ECO Number: 5425422-TA001**

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Part	MLB
Revision	B01
Component	MLB
Severity	High
ECO Issue Date	Nov 97
Type of Notification	Action not required
Change Description	Fix MLB problem for DS7100R

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### **Description**

**Severity:** High

**Description:** System boot delay of over 30 minutes.

**Symptom:** N/A

### **Solution**

Change E29 from 19-12799-61 to 21-39063-61.

### **Compatibility**

N/A

### **Customer Impact/Recommendations:**

No customer impact since it will be implemented during the manufacturing process..



## **ECO Number: 5423594-TA003**

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Part	OPC
Revision	C02
Component	OCP
Severity	High
ECO Issue Date	Feb 98
Type of Notification	Customer action not required
Change Description	Add components to OCP for DS7100 and DS7105

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### **Description**

Noise from OCP to LCD module which makes unit critical to meet Digital EMI requirement of under 3 dB

**Severity:** High

**Problem:** N/A.

### **Solution**

Add 10 pieces of 16-35517-01 (BEAD) on J3 and change E4 from F132 to HCT132.

### **Compatibility:**

N/A

### **Customer Impact/Recommendations:**

No customer impact since this was a manufacturing yield improvement.

## **ECO Number: PC932-TA002**

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Part	Krnl
Revision	B01
Component	Krnl
Severity	High
ECO Issue Date	Feb 98
Type of Notification	Action not required
Change Description	Phase in BCIQ for DS7100 - Viper

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### **Description**

Phase in BCIQ

**Severity:** High

**Problem:** N/A.

### **Solution**

Change 36-44177-11 minimum rev. from A to B

### **Compatibility:**

N/A

### **Customer Impact/Recommendations:**

No customer impact since this was a manufacturing yield improvement.

## **ECO Number: 54-25422-TA003**

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Part	MLB
Revision	B03
Component	MLB
Severity	Medium
ECO Issue Date	Feb 98
Type of Notification	Action not required
Change Description	Solder Mask problems for DS7100R

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### **Description**

The solder mask on the mounting holes will affect FCC test results.

**Severity:** Medium

**Problem:** N/A.

### **Solution**

Remove solder mask on the mounting holes on side 1 and 2.

### **Compatibility:**

N/A

### **Customer Impact/Recommendations:**

No customer impact since this was a manufacturing yield improvement.

## **ECO Number: 54-25422-TA003A**

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Part	MLB
Revision	B03
Component	MLB
Severity	Medium
ECO Issue Date	Feb 98
Type of Notification	Action not required
Change Description	Solder Mask problems for DS7100R

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### **Description**

1. The solder mask on the mounting holes will affect FCC test result.
2. Modify 50-25421-01 to avoid short circuit between +5V and Gnd at locating pin caused from PCB being scratched by the locating pin.
3. Add break area on PCB to improve manufacturing process.
4. The new rev of 50-25421-01 etch is not correct.

**Severity:** Medium

**Problem:** FCC Test results negatively affected.

### **Solution**

Remove solder mask on the mounting holes on side 1 and 2.

1. Enlarge the etch-free area in the inner layers around the locating hole to guarantee no short circuit will happen between any two layers even when locating hole was scratched by the locating pin during production process.
2. Add break area and two tooling holes to break area. (The mark-up drawing is attached.)
3. Change 50-25421-01 new rev from D01 to C02.

### **Compatibility:**

N/A

### **Customer Impact/Recommendations:**

No customer impact since this was a manufacturing yield improvement.

## **ECO Number: 54-24480-TA016**

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Part	MLB
Revision	B03
Component	MLB
Severity	Medium
ECO Issue Date	Mar 98
Type of Notification	Action not required
Change Description	Modify MLB locating holes for DS7100 and DS7105

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### **Description**

The locating holes can be scratched by the locating pin during the manufacturing process which may cause a short between +5V and Gnd.

**Severity:** Medium

**Problem:** N/A

### **Solution**

1. Enlarge the etch-free area in the inner layers around the locating hole to guarantee that no short circuit will occur between any two layers, even when the locating hole is scratched by the locating pin during the production process.
2. Recommend to enlarge the ring space of locating holes from 20 mil to 70 mil.

### **Compatibility:**

N/A

### **Customer Impact/Recommendations:**

No customer impact since this will be implemented by the PCB vendor.